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East Fishkill Facility
2070 Route 52, B300/482
Hopewell Junction, NY 12533-6531

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of _____:

May 18, 2004

William G. America, et al. _____:

Examiner:

Serial No. 10/709,630 _____:

IBM Corporation, IPLAW
Dept. 18G/Bldg. 300-482
2070 Route 52
Hopewell Junction
New York 12533-6531

Filed: May 18, 2004 _____:

Title: METHOD FOR REACTIVE
ION ETCH PROCESSING
OF A DUAL DAMASCENE
STRUCTURE _____:

INFORMATION DISCLOSURE STATEMENT

Commissioner of Patents and Trademarks
Washington, D.C. 20231

Sir:

Pursuant to the duty of disclosure set forth in 37 CFR 1.56, and further pursuant to 37 CFR 1.97 and 37 CFR 1.98, Applicants hereby respectfully submit copies of the following prior patents and publications as listed on Form PTO-1449, attached hereto.

Respectfully submitted,
William G. America, et al.

By: James J. Cioffi
James J. Cioffi, Attorney
Registration No. 51,564
Tel. (845)894-3363

Enclosure

FIS920040053US1

- 1 -

INFORMATION DISCLOSURE CITATION

(Use several sheets if necessary)

ATTY DOCKET NO.
FIS920040053US1SERIAL NO.
10/709,630

AMERICA ET AL.

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GROUP

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
						YES	NO

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

	1	Multilevel Wiring Technology for Leading-Edge CMOS Devices in the 65 nm Generation Hybrid Low Dielectric Constant Film Structure copper Wiring Module Reduced Wiring Capacitance and Supports Fine Fabrication.
	2	R. Kanamura, Y. Ohaka, M. Fukasawa, K. Tabuchi, K. Nagahata, S. Shibuki, M. Muramatsu, H. Miyajima, T. Usui, A. Kajita, H. Shibata, and S. Kadamura; "Integration of Cu/low-k Dual-Damascene Interconnects with a Porous PAE/SiOC Hybrid Structure for 65nm-node High Performance eDram

EXAMINER

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*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.